

2.66inch e-Paper (G) User Manual







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1. OVERVIEW

2.66 e-Paper (G) is an reflective electrophoretic technology display module on an active matrix TFT substrate. The panel is capable of displaying black, white, yellow and red images depending on the associated lookup table used. The circuitry on the panel includes an integrated gate and source driver, timing controller, oscillator, DC-DC boost circuit, and memory to store the frame buffer and lookup tables, and additional circuitry to control VCOM and border settings



2. FEATURES

- ♦ Highlight Red and Yellow color
- ♦ High contrast
- ♦ High reflectance
- ♦ Ultra wide viewing angle
- ♦ Ultra low power consumption
- ♦ Pure reflective mode
- ♦ Bi-stable display
- ♦ Antiglare hard-coated front-surface
- ♦ Low current deep sleep mode
- ♦ On-chip display RAM
- ♦ Waveform can stored in On-chip OTP
- ♦ Serial peripheral interface available
- ♦ On-chip oscillator
- ♦ On-chip booster and regulator control for generating VCOM, Gate and Source driving voltage
- ♦ I²C signal master interface to read external temperature sensor
- ♦ Available in COG package

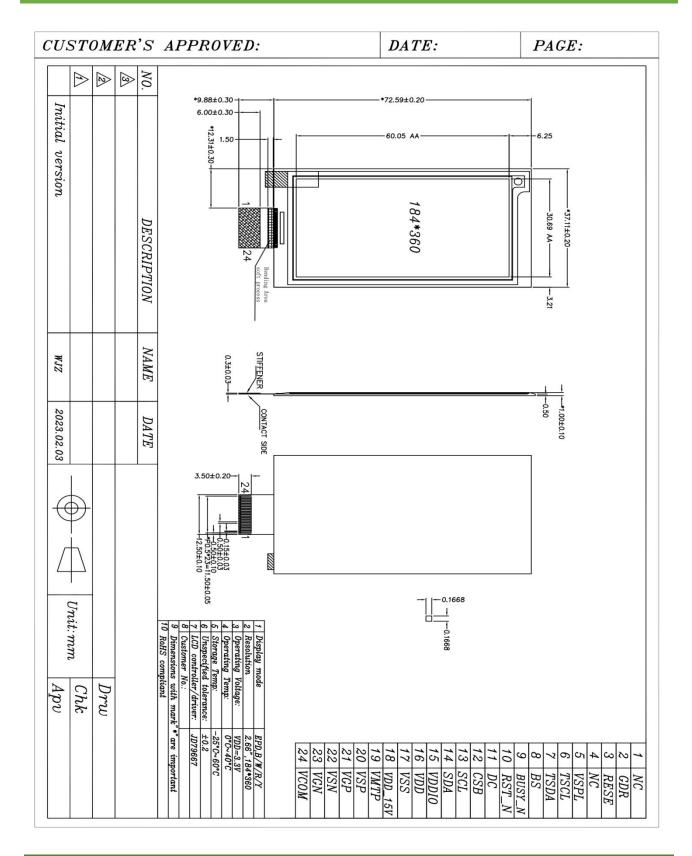


3. MECHANICAL SPECIFICATION

Parameter	Specification	Unit	Remark
Screen Size	2.66	Inch	
Display Resolution	184(H) x 360(V)	Pixel	DPI:152
Active Area	30.69 x 60.05	mm	
Pixel Pitch	0.1668 x 0.1668	mm	
Pixel Configuration	Rectangle		
Outline Dimension	37.11(H) x 72.59 (V) x 1.0(D)	mm	
Weight	4.06±0.5	g	
	Shorie and shories and shories are shories	J. d. Wolf	



4. MECHANICAL DRAWING OF EPD MODULE





5. INPUT/OUTPUT PIN ASSIGNMENT

NO.	Name	I/O	Description	Remark
1	NC		Do not connect with other NPC pins	Keep Open
2	GDR	0	N-MOS Gate Control	
3	RESE	Р	Current Sense Input for the Control Loop	
4	NC	NC	Do not connect with other NC pins	Keep Open
5	VSPL	Р	Positive Source voltage	
			I ² C clock for external temperature sensor	
6	TSCL	0	(I ² C interface need external pull high resistance.)	
			Must pull high or low if not used.	
			I ² C data for external temperature sensor	
7	TSDA	I/O	(l ² C interface need external pull high resistance.)	
			Must pull high or low if not used. (Default low)	
8	BS	I	Input interface setting	
9	BUSY_N	0	This pin indicates the driver status.	
10	RST_N	I	Global reset pin. Low reset. (normal pull high)	
11	DC	I	Serial communication Command/Data input	
12	CSB	I	Serial communication chip select	
13	SCL	I	Serial communication clock input	
14	SDA	I/O	Serial communication data input	
15	VDDIO	Р	IO voltage supply	
16	VDD	Р	Digital/Analog power.	
17	VSS	Р	Ground	
18	VDD_15V	Р	1.5V voltage input & output	
19	VMTP	Р	MTP program power (10.1V)	
20	VSP	Р	Positive Source voltage	
21	VGP	Р	Positive Gate driving voltage	
22	VSN	Р	Negative Source driving voltage	
23	VGN	Р	Negative Gate voltage	
24	VCOM	0	VCOM driving voltage	

Note: I: Input, O: Output, P: Power, D: Dummy, S: Shorted line, M: Mark, PI: Power input, PO: Power output, I/O: Input/Output. PS: Power setting, C: Capacitor pin.





6. ELECTRICAL CHARACTERISTICS

6.1 ABSOLUTE MAXIMUM RATING

Parameter	Symbol	Rating	Unit
	VDD,		
Logic supply voltage	AVDD,	-0.3 to +6.0	V I
Logic supply voltage	VDDIO,	-0.3 to +0.0	V
	VDD1, VPP		
Logic Input voltage	VI	-0.3 to VDDIO +0.3	V
Operating Temp range	TOPR	0 to +40	°C
Storage Temp range	TSTG	-25 to+60	°C
Optimal Storage Temp	TSTGo	23±2	°C
Optimal Storage Humidity	HSTGo	55±10	%RH

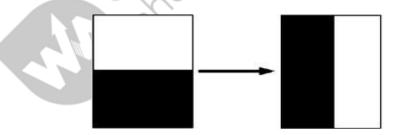
Note: Absolute Maximum Ratings are stress ratings. Stresses in excess of these ratings can cause permanent damage to the device. Functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this data sheet is not implied. Exposing device to the absolute maximum ratings in a long period of time may degrade the device and affect its reliability.



6.2 PANEL DC CHARACTERISTICS

Parameter	Symbol	Condition	Applicable pin	Min.	Тур.	Max.	Unit
Single ground	Vss	-		-	0	-	V
Logic supply voltage	V _{IO}	-	VIO	2.3	3.3	3.6	V
Core logic voltage	V_{DD}		VDD	2.3	3.3	3.6	V
High level input voltage	V _{IH}	-	-	0.7V _{IO}	-	V _{IO}	V
Low level input voltage	VıL	-	-	GND	-	0.3V _{DD}	V
High level output voltage	V _{ОН}	IOH = 400uA	-	V _{IO} -0.4	-	-	V
Low level output voltage	V _{OL}	IOL = -400uA	-	GND	-	GND +0.4	V
Typical power	P _{TYP}	V _{CI} =3.3V	-	-	9.9	-	mW
Deep sleep mode	P _{STPY}	V _{CI} =3.3V	-	-	0.003	-	mW
Typical operating current	lopr_V _{CI}	V _{CI} =3.3V	-	-	3	-	mA
Image update time	-	25 °C	-	-	25	-	sec
Stand-by current	I _{st} _V _{CI}		-	-	1	5	uA

Notes: 1. The typical power is measured with following transition from horizontal 2 scale pattern to vertical.



- 2. The deep sleep power is the consumed power when the panel controller is in deep sleep mode.
- 3. The listed electrical characteristics are only guaranteed under the controller & waveform provided by Waveshare.



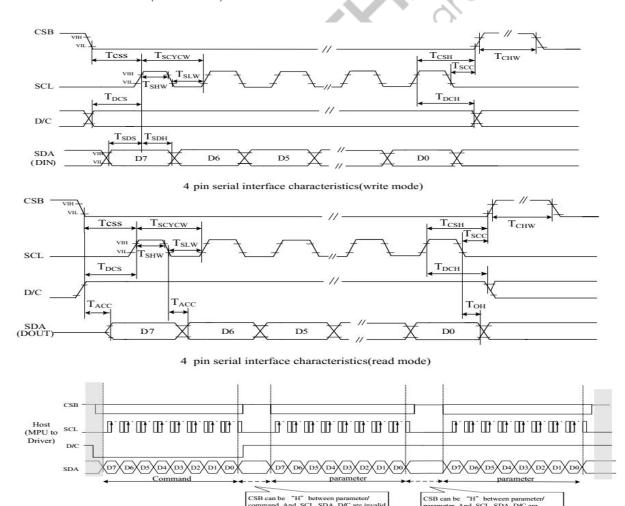


6.3 AC CHARACTERISTICS

6.3.1 MCU INTERFACE SELECTION

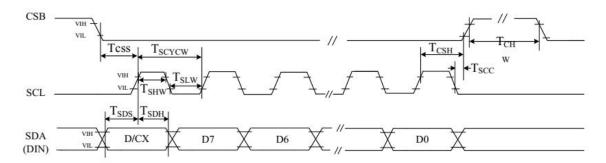
The 3-wire/4-wire serial port as communication interface for all the function and command setting. 3-wire/4-wire engine act as a "slave mode" for all the time, and will not issue any command to the 3-wire/4-wire bus itself. Under read mode, 3-wire/4-wire engine will return the data during "Data phase". The returned data should be latched at the rising edge of SCL by external controller. Data in the "Hi-Z phase" will be ignored by 3-wire/4-wire engine during write operation, and should be ignored during read operation also. During read operation, external controller should float SDA pin under "Hi-Z phase" and "Data phase".

6.3.2 MCU SERIAL INTERFACE (4-WIRE SPI)

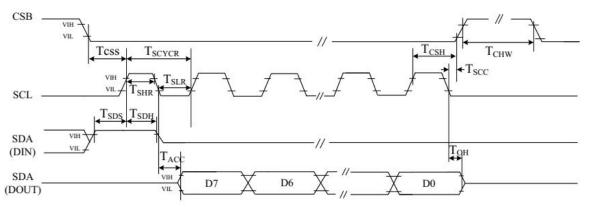




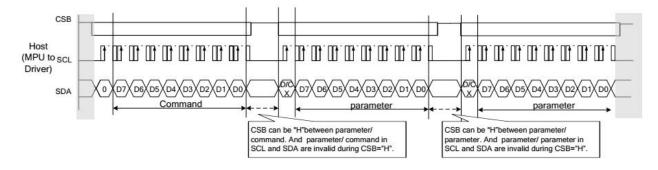
6.3.3 MCU SERIAL INTERFACE (3-WIRE SPI)



3 pin serial interface characteristics (write mode)



3 pin serial interface characteristics (read mode)





7. COMMAND TABLE

Addross	command								E	3it		
Address	command	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0	Code
		w	0	0	0	0	0	0	0	0	0	00H
R00H	Panel setting (PSR)	w	1	RES[1]	RES[0]	PST_MODE	10.0	UD	SHL	SHD_N	RST_N	0Fh
		w	1	LUT_EN	-	FOPT	VCMZ	TS_AUTO	TIEG	NORG	VC_LUTZ	09h
		w	0	0	0	0	0	0	0	0	1	01H
	3	w	-1	-	-	1940		V_MODE	VSC_EN	VDS_EN	VDG_EN	07h
	N .	w	1	(-3)					:=	VGPN [1]	VGPN [0]	00h
R01H	Power setting (PWR)	w	1		VSPL_0[6]	VSPL_0[5]	VSPL_0[4]	VSPL_0[3]	VSPL_0[2]	VSPL_0[1]	VSPL_0[0]	00h
		w	1		VSP_1[6]	VSP_1 [5]	VSP_1 [4]	VSP_1 [3]	VSP_1 [2]	VSP_1 [1]	VSP_1 [0]	00h
	8	w	1	123	VSN_1[6]	VSN_1[5]	VSN_1[4]	VSN_1[3]	VSN_1[2]	VSN_1[1]	VSN_1[0]	00h
	18	w	1	-	VSPL_1[6]	VSPL_1[5]	VSPL_1[4]	VSPL_1[3]	VSPL_1[2]	VSPL_1[1]	VSPL_1[0]	00h
		w	0	0	0	0	0	0	0	1	0	02H
R02H	Power OFF(POF)	w	1	-	-			15	-	(5)	EDSE	00h
		w	0	0	0	0	0	0	0	1	1	03H
	Power off Sequence	w	1	T_VDS_	OFF2[1:0]	T_VDPG	OFF[1:0]	T_VDS	ON[1:0]	T_VDS	OFF[1:0]	00h
R03H	Setting(PFS)	w	1	27	VGP_LE	0.00		To be desired		EXT[3:0]		54
		w	1	5	XON	DLY	*		XON	LEN	3	44
R04H	Power ON (PON)	w	0	0	0	0	0	0	1	0	0	04H
- 3		w	0	0	0	0	0	0	1	1	0	06H
		w	1	0.00	_	8.00		1000	SFT[1:0]	PHA S	FT[1:0]	00h
	8	w	1	1.00	-	1,51,51	1018	No. Train	ON[5:0]			02h
	Booster Soft Start	w	1	123					OFF[5:0]			07h
R06H	(BTST)	w	1		_			111	ON[5:0]		3	02h
		w	1	5.40	-				OFF[5:0]			07h
		w	1		_			1000000	ON[5:0]		3	02h
	8	w	1	-			PHC_OFF[5:0]					07h
		w	0	0	0	0	0	0	1	1	1	07H
R07H	Deep Sleep(DSLP)	w	1	1	0	1	0	0	1	0	1	A5h
	Data Otast	w	0	0	0	0	1	0	0	0	0	10H
R10H	Data Start transmission (DTM)	w	1	#	#	#	#	#	#	#	#	00H
	,	w	0	0	0	0	1	0	0	0	1	11H
R11H	Data Stop (DSP)	R	1	Data_flag	-	-		-	-	-		2.2
-		w	0	0	0	0	1	0	0	1	0	12H
R12H	Display Refresh (DRF)		1	-	-			-			AC/DC	
		W	1	-		(· · ·	0.		Gate_seq	-	VCOM	00H
R17H	Auto sequence (AUTO)	W	0	0	0	0	1	0	1	1	1	17H
	(A010)	w	1	Code[7]	Code[6]	Code[5]	Code[4]	Code[3]	Code[2]	Code[1]	Code[0]	A5h
R30H	PLL control (PLL)	W	0	0	0	1	1	0	0	0	0	30H
250000000000000000000000000000000000000		w	1	•	•			Dyna	_		2:0]	02h
Dist	Temperature Sensor	W	0	0	1	0	0	0	0	0	0	40H
R40H	Command (TSC)	R	1	D10/TS[7]	D9/TS[7]	D8/TS[6]	D7/TS[5]	D6/TS[4]	D5/TS[3]	D4/TS[2]	D3/TS[1]	**
		R	1	D2/ TS[9]	D1/TS[8]	D0	***	19		*		-
R41H	Temperature Sensor	w	0	0	1	0	0	0	0	0	1	41H
	Calibration (TSE)	w	1	TSE	-		TO[4]	TO[3]	TO[2]	TO[1]	TO0]	00h
	8	w	0	0	1	0	0	0	0	1	0	42H
R42H	Temperature Sensor	W	1	WATTR[7]	WATTR[6]	WATTR[5]	WATTR[4]	WATTR[3]	WATTR[2]	WATTR[1]	WATTR[0]	00h
	Write (TSW)	W	1	WMSB[7]	WMSB[6]	WMSB[5]	WMSB[4]	WMSB[3]	WMSB[2]	WMSB[1]	WMSB[0]	00h
		W	1	WLSB[7]	WLSB[6]	WLSB[5]	WLSB[4]	WLSB[3]	WLSB[2]	WLSB[1]	WLSB[0]	00h
R43H	Temperature Sensor	W	0	0	1	0	0	0	0	1	1	43H



	Read (TSR)	R	1	RMSB[7]	RMSB[6]	RMSB[5]	RMSB[4]	RMSB[3]	RMSB[2]	RMSB[1]	RMSB[0]	-
		R	1	RLSB[7]	RLSB[6]	RLSB[5]	RLSB[4]	RLSB[3]	RLSB[2]	RLSB[1]	RLSB[0]	-
	VCOM and DATA	w	0	0	1	0	1	0	0	0	0	50H
R50H	interval setting (CDI)	W	1	VBD[2]	VBD[1]	VBD[0]	DDX	CDI[3]	CDI[2]	CDI[1]	CDI[0]	97h
	Lower Power	w	0	0	1	0	1	0	0	0	1	51H
R51H	Detection (LPD)	R	1		-		r • 5	6.0		100	LPD	
		w	0	0	1	1	0	0	0	0	1	61H
		w	1		(4)	-	100	-	-	HRES(9)	HRES(8)	00h
R61H	Resolution	w	-1	HRES(7)	HRES(6)	HRES(5)	HRES(4)	HRES(3)	HRES(2)	0	0	00h
	setting(TRES)	w	1			-			-	VRES(8)	VRES(0)	00h
		w	1	VRES(7)	VRES(6)	VRES(5)	VRES(4)	VRES(3)	VRES(2)	VRES(1)	VRES(0)	00h
		w	0	0	1	1	0	0	1	0	1	65H
		w	1		-			0.00		S_start(9)	S_start(8)	00h
R65H	Gate/Source Start	w	1	S_start(7)	S_start(6)	S_start(5)	S_start(4)	S_start(3)	S_start(2)	0	0	00h
110011	Setting(GSST)	w	1	-	0_0414(0)	-	0_0.0.1.(4)	0_0(0)	0_0.0.1(2)	G_start(9)	G_start(8)	00h
		w	1	G_start(7)	G_start(6)	G_start(5)	G_start(4)	G_start(3)	G_start(2)	G_start(1)	G_start(0)	00h
		w	0	0_3tart(7)	1	1	1	0_3441(0)	0_3tan(2)	0_3881(1)	0_3tan(0)	70H
		R	1	0	0	0	0	0	0	1	1	05h
R70H	REVISION (REV)	R	1	0	0	0	0	0	0	1	0	02h
		R	1	0	0	0	0	0	0	0	1	01h
		W	0	1	0	0	0	0	0	0	0	80 H
R80H	Auto Measure Vcom (AMV)		0765			Samuel Control	7,3270	0.702	AMVS	AMV	- 15	NT-700450
	(/30//)	w	1	P[1]	P[0]	AMVT[1]	AMVT[0] 0	XON 0	C000430000	Line Period	AMVE	00h
R81H	Vcom Value (VV)	W	0	1	57	0	8553	355	0	0	1	81H
		R	1	-	VV[6]	VV[5]	VV[4]	VV[3]	VV[2]	VV[1]	VV[0]	-
R82H	Vcom_DC Setting register(VDCS)	w	0	1	0	0	0	0	0	1	0	82H
		w	1	MTP_VCM	VDCS[6]	VDCS[5]	VDCS[4]	VDCS[3]	VDCS[2]	VDCS[1]	VDCS[0]	00h
	-	w	0	1	0	0	0	0	0	1	1	83H
		w	1	-	-	-	-	-	-	HRST(9)	HRST(8)	00h
		W	1	HRST(7)	HRST(6)	HRST(5)	HRST(4)	HRST(3)	HRST(2)	0	0	00h
	1407 30 10000 70	w	1	*		*			-	HRED(9)	HRED(8)	00h
R83H	Partial Window	W	1	HRED(7)	HRED(6)	HRED(5)	HRED(4)	HRED(3)	HRED(2)	0	0	00h
	(PTLW)	W	1	-	-	-	-	-	•	VRST(9)	VRST(8)	00h
		W	1	VRST(7)	VRST(6)	VRST(5)	VRST(4)	VRST(3)	VRST(2)	VRST(1)	VRST(0)	00h
		W	1	•		•				VRST(9)	VRST(8)	00h
		W	1	VRST(7)	VRST(6)	VRST(5)	VRST(4)	VRST(3)	VRST(2)	VRST(1)	VRST(0)	00h
		W	1	•	15/		1.5				PMOD	00h
R90H	Program mode(PGM)	w	0	1	0	0	1	0	0	0	0	90H
R91H	Active Program(APG)	w	0	1	0	0	1	0	0	0	1	91H
R92H	Read MTP data	W	0	1	0	0	1	0	0	1	0	92H
. 10211	(RMTP)	R	1	#	#	#	#	#	#	#	#	85
R9EH	REVISION2 (REV2)	W	0	1	0	0	1	1	1	1	0	9EH
		R	1	0	0	0	0	0	0	0	1	01h
R9FH	Read MTP Reserved	W	0	1	0	0	1	1	1	1	1	9FH
1731.11	Bytes(RMRB)	R	1	#	#	#	#	#	#	#	#	3*
			100001	32	1	1	0	0	0	1	1	E3H
THE STATE OF THE S		W	0	1	Annual Section (Contraction Contraction)						38	
RE3H	Power saving(PWS)	w	1	VCOM_W	VCOM_W	VCOM_W	VCOM_W [0]	SD_W[3]	SD_W[2]	SD_W[2]	SD_W[0]	00h
THE STATE OF THE S		U 1000	97.00		Annual Section (Contraction Contraction)		VCOM_W [0]	SD_W[3] 0	SD_W[2]	SD_W[2] 0		00h E4H
RE3H	Power saving(PWS)	w	1 0	VCOM_W [3]	VCOM_W [2]	VCOM_W [1]	[0]			0 LVD_SEL	SD_W[0] 0 LVD_SEL	9778500
THE STATE OF THE S		w w	1	VCOM_W [3]	VCOM_W [2]	VCOM_W [1]	0	0	1	0	SD_W[0]	E4H

R00H		Bit									
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0	Code
PSR	W	0	0	0	0	0	0	0	0	0	00H
1 st Parameter	W	1	RES[1]	RES[0]	PST_MODE	-	UD	SHL	SHD_N	RST_N	0Fh
2 nd Parameter	W	1	LUT_EN	(-)	FOPT	VCMZ	TS_AUTO	TIEG	NORG	VC_LUTZ	09h

NOTE: "-" Don't care, can be set to VDD or GND level



Description	-The commar	nd defines as :	
	1 st paramete	er	
	Bit	Name	Description
	0	RST_N	RST_N function 1: no effect. (default) 0: Booster OFF, Register data are set to their default values, and Source/Boder/Vcom: floating
	1	SHD_N	SHD_N function 0 : Booster OFF, register data are kept, and Source/Boder/Vcom are kept 0V or floating. 1 : Booster on. (default)
	2	SHL	SHL function 0: Shift left; First data=Sn→Sn-1 →→S2→Last data=S1. 1: Shift right: First data=S1→S2 →→Sn-1→Last data=Sn. (default)
	3	UD	UD function 0:Scan down; First line=Gn→Gn-1 →→G2→Last line=G1. 1:Scan up; First line=G1→G2 →→Gn-1→Last line=Gn. (default)
	5	PST_MODE	Power switch operation mode 0:Power switching time in the period of frame scanning.(default) 1:Power switching time in the external period before frame scanning.
	7-6	RES[1,0]	Resolution setting 00: Display resolution is 200x384 (default) 01: Display resolution is 184x384 10: Display resolution is 168x384 11: Display resolution is 200x200

Bit	Name	Description
		VCOM status function
0	VC LUTZ	0 : No effect
	_	1 : After refreshing display,the output of VCOM is set to floating
		automatically (default)
		VCOM status function
1	NORG	0 : No effect (default)
		1 : After refreshing display, VCOM is tied to GND before power off
	TIEG	VGN power off status function
2		0 : No effect (default)
		1 : Power off, VGN will be tied to GND
		Temperature sensing will be activated automatically one time
		0 : Before enabling booster, Temperature Sensor will be activated
3	TS AUTO	automatically one time.
		1: When RST N low to high, Temperature Sensor will be activated
		automatically one time. (default)
		VCOM status function
4	VCMZ	0 : No effect (default)
		1 : VCOM is always floating
		FOPT function
_		0: Scan 1 frame after waveform finished(default)
5	FOPT	1: No scan after waveform finished and switch the source channel output t
		Hiz.

Priority of VCOM setting: VCMZ > NORG > FOPT > VC_LUTZ

FOPT setting is part of refreshing display. FOPT: Power off floating.

Notes:

- tes:
 Non-select gate line keep at VGN for DSP/DRF and AMV
 Dummy source line follow LUTC for DSP/DRF
 When SHD_N become low, DCDC will turn off. Register and SRAM data will keep until VDD turn off.SD output and VCOM will base on previous condition. It may have two condition:0V or
- floating.

 When RST_N become low, driver will reset. All register will reset to default value. All of the driver's functions will disable. Source/Gate/Border/VCOM will be released to floating

Restriction



R01H						Bit					
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0	Code
PWR	W	0	0	0	0	0	0	0	0	1	01h
1 st Parameter	W	1	=	-	-	-	V_MODE	VSC_EN	VDS_EN	VDG_EN	07h
2 nd Parameter	W	1	-		-	8	-	-	VGPN [1]	VGPN [0]	00h
3 rd Parameter	W	1	-		VSPL_0 [6:0]						00h
4 th Parameter	W	1	8		VSP_1 [6:0]						00h
5 th Parameter	W	1	(F)	VSN_1 [6:0]						00h	
6 th Parameter	W	1	-				VSPL_1 [6:0]			00h

Description

-The command defines as :

1st Parameter:

Bit	Name	Description
0	VDG_EN	Gate power selection. 0 : External gate power from VGP/VGN pins. 1 : Internal DCDC function for generate VGP/VGN. (default)
1	VDS_EN	Source power selection. 0 : External source power from VSP/VSN pins. 1 : Internal regulator function for generate VSP/VSN (default)
2	VSC_EN	Source LV power selection. 0 : External source power from VSPL pins. 1 : Internal regulator function for generate VSPL (default)
3	V_MODE	Source Power switching mode. 0: Mode0(default) 1: Mode1

2nd Parameter:

Ziid i araille	ter.	na rarameter.							
Bit	Name	Description							
		VGPN Voltage Level.	\Box						
		00: VGP=20 v, VGN=-20v (default)							
1-0	VGPN	01: VGP=17 v, VGN=-17v							
		10: VGP=15 v, VGN=-15v							
		11: VGP=10 v, VGN=-10v							

3rd & 4th & 6th Parameter: Internal VSP_1/VSPL_0/ VSPL_1 power selection

Bit	Name				De	scrip	tion			
		Internal VS	Internal VSP & VSPL power selection.							
		bit[6:0	0]	Voltage(V) bit [6:0]		Voltage(V) bit [6:0		0])] Voltage(V	
		0000000	00h	3	0101001	29h	7.1	1010010	52h	11.2
		0000001	01h	3.1	0101010	2Ah	7.2	1010011	53h	11.3
		0000010	02h	3.2	0101011	2Bh	7.3	1010100	54h	11.4
		0000011	03h	3.3	0101100	2Ch	7.4	1010101	55h	11.5
		0000100	04h	3.4	0101101	2Dh	7.5	1010110	56h	11.6
		0000101	05h	3.5	0101110	2Eh	7.6	1010111	57h	11.7
		0000110	06h	3.6	0101111	2Fh	7.7	1011000	58h	11.8
		0000111	07h	3.7	0110000	30h	7.8	1011001	59h	11.9
		0001000	08h	3.8	0110001	31h	7.9	1011010	5Ah	12
		0001001	09h	3.9	0110010	32h	8	1011011	5Bh	12.1
		0001010	0Ah	4	0110011	33h	8.1	1011100	5Ch	12.2
		0001011	0Bh	4.1	0110100	34h	8.2	1011101	5Dh	12.3
		0001100	0Ch	4.2	0110101	35h	8.3	1011110	5Eh	12.4
		0001101	0Dh	4.3	0110110	36h	8.4	1011111	5Fh	12.5
		0001110	0Eh	4.4	0110111	37h	8.5	1100000	60h	12.6
		0001111	0Fh	4.5	0111000	38h	8.6	1100001	61h	12.7
		0010000	10h	4.6	0111001	39h	8.7	1100010	62h	12.8
	V00 4	0010001	11h	4.7	0111010	3Ah	8.8	1100011	63h	12.9
	VSP_1 &	0010010	12h	4.8	0111011	3Bh	8.9	1100100	64h	13
0.0	VSPL 0	0010011	13h	4.9	0111100	3Ch	9	1100101	65h	13.1
6-0	VSPL_0 & VSPL_1	0010100	14h	5	0111101	3Dh	9.1	1100110	66h	13.2
	VSPL_1	0010101	15h	5.1	0111110	3Eh	9.2	1100111	67h	13.3



0010110	16h	5.2	0111111	3Fh	9.3	1101000	68h	13.4	
0010111	17h	5.3	1000000	40h	9.4	1101001	69h	13.5	
0011000	18h	5.4	1000001	41h	9.5	1101010	6Ah	13.6	
0011001	19h	5.5	1000010	42h	9.6	1101011	6Bh	13.7	
0011010	1Ah	5.6	1000011	43h	9.7	1101100	6Ch	13.8	
0011011	1Bh	5.7	1000100	44h	9.8	1101101	6Dh	13.9	
0011100	1Ch	5.8	1000101	45h	9.9	1101110	6Eh	14	
0011101	1Dh	5.9	1000110	46h	10	1101111	6Fh	14.1	
0011110	1Eh	6	1000111	47h	10.1	1110000	70h	14.2	
0011111	1Fh	6.1	1001000	48h	10.2	1110001	71h	14.3	
0100000	20h	6.2	1001001	49h	10.3	1110010	72h	14.4	
0100001	21h	6.3	1001010	4Ah	10.4	1110011	73h	14.5	
0100010	22h	6.4	1001011	4Bh	10.5	1110100	74h	14.6	
0100011	23h	6.5	1001100	4Ch	10.6	1110101	75h	14.7	
0100100	24h	6.6	1001101	4Dh	10.7	1110110	76h	14.8	
0100101	25h	6.7	1001110	4Eh	10.8	1110111	77h	14.9	
0100110	26h	6.8	1001111	4Fh	10.9	1111000	78h	15	
0100111	27h	6.9	1010000	50h	11	othor	c.	15	
0101000	28h	7	1010001	51h	11.1	other		15	

	5th P	arameter:	Internal \	/SN_	_1 power s	selection					
	Bit	Name					scrip	tion			
			Internal VS	N po	wer selection	on.					
			bit[6:0)1	Voltage(V)	bit [6:0)1	Voltage(V)	bit [6:0)]	Voltage(\
			0000000	00h	-3	0101001	29h	-7.1	1010010	52h	-11.2
			0000001	01h	-3.1	0101010	2Ah	-7.2	1010011	53h	-11.3
			0000010	02h	-3.2	0101011	2Bh	-7.3	1010100	54h	-11.4
			0000011	03h	-3.3	0101100	2Ch	-7.4	1010101	55h	-11.5
			0000100	04h	-3.4	0101101	2Dh	-7.5	1010110	56h	-11.6
			0000101	05h	-3.5	0101110	2Eh	-7.6	1010111	57h	-11.7
			0000110	06h	-3.6	0101111	2Fh	-7.7	1011000	58h	-11.8
			0000111	07h	-3.7	0110000	30h	-7.8	1011001	59h	-11.9
			0001000	08h	-3.8	0110001	31h	-7.9	1011010	5Ah	-12
			0001001	09h	-3.9	0110010	32h	-8	1011011	5Bh	-12.1
			0001010	0Ah	-4	0110011	33h	-8.1	1011100	5Ch	-12.2
			0001011	0Bh	-4.1	0110100	34h	-8.2	1011101	5Dh	-12.3
			0001100	0Ch	-4.2	0110101	35h	-8.3	1011110	5Eh	-12.4
			0001101	0Dh	-4.3	0110110	36h	-8.4	1011111	5Fh	-12.5
			0001110	0Eh	-4.4	0110111	37h	-8.5	1100000	60h	-12.6
			0001111	0Fh	-4.5	0111000	38h	-8.6	1100001	61h	-12.7
			0010000	10h	-4.6	0111001	39h	-8.7	1100010	62h	-12.8
			0010001	11h	-4.7	0111010	3Ah	-8.8	1100011	63h	-12.9
			0010010	12h	-4.8	0111011	3Bh	-8.9	1100100	64h	-13
	0.0	VON 4	0010011	13h	-4.9	0111100	3Ch	-9	1100101	65h	-13.1
	6-0	VSN_1	0010100	14h	-5	0111101	3Dh	-9.1	1100110	66h	-13.2
			0010101	15h	-5.1	0111110	3Eh	-9.2	1100111	67h	-13.3
			0010110	16h	-5.2	0111111	3Fh	-9.3	1101000	68h	-13.4
			0010111	17h	-5.3	1000000	40h	-9.4	1101001	69h	-13.5
			0011000	18h	-5.4	1000001	41h	-9.5	1101010	6Ah	-13.6
			0011001	19h	-5.5	1000010	42h	-9.6	1101011	6Bh	-13.7
			0011010	1Ah	-5.6	1000011	43h	-9.7	1101100	6Ch	-13.8
			0011011	1Bh	-5.7	1000100	44h	-9.8	1101101	6Dh	-13.9
			0011100	1Ch	-5.8	1000101	45h	-9.9	1101110	6Eh	-14
			0011101	1Dh	-5.9	1000110	46h	-10	1101111	6Fh	-14.1
			0011110	1Eh	-6	1000111	47h	-10.1	1110000	70h	-14.2
			0011111	1Fh	-6.1	1001000	48h	-10.2	1110001	71h	-14.3
			0100000	20h	-6.2	1001001	49h	-10.3	1110010	72h	-14.4
			0100001	21h	-6.3	1001010	4Ah	-10.4	1110011	73h	-14.5
			0100010	22h	-6.4	1001011	4Bh	-10.5	1110100	74h	-14.6
			0100011	23h	-6.5	1001100	4Ch	-10.6	1110101	75h	-14.7
			0100100	24h	-6.6	1001101	4Dh	-10.7	1110110	76h	-14.8
			0100101	25h	-6.7	1001110	4Eh	-10.8	1110111	77h	-14.9
			0100110	26h	-6.8	1001111	4Fh	-10.9	1111000	78h	-15
			0100111	27h	-6.9	1010000	50h	-11	other		-15
	1		0101000	28h	-7	1010001	51h	-7.1			



Notes:

- VSP_0/VSN_0 voltage output is ±15 V fixed value.
 When switching Mode0 or Mode1, the voltage output is: Mode0: VSP_0(+15) / VSN_0 (-15) / VSPL_0 (+3~+15) Mode1: VSP_1(+3 ~ +15) / VSN_1(-3 ~ -15) / VSPL_1(+3 ~ +15)

	Mode0	Mode1
VSP	VSP_0(+15)	VSP_1(+3~+15)
VSN	VSN_0(-15)	VSN_1(-3~-15)
VSPL	VSPL_0(+3~+15)	VSPL_1(+3~+15)

3. If gate voltage is set to +/-15v, +/-10v, IC will auto correct source voltage as follows I. VGP- VSP_0 / VSPL_0 / VSP_1 / VSPL_1 >= 2v II. $VGN-VSN_0 / VSN_1 >= -2v$ For example:

	symbol	Voltage setting	Real Voltage	
	VGP	10v	+10v	
	VGN	10v	-10v	
	VSP_0	+15v	+8v	
	VSN_0	-15v	-8v	
.,	VSP_1	+5v	+5v	
Voltage	VSN_1	-5v	-5v	
	VSPL	+15v	+8v	
	VCOMH	+15v+(-2v)	+8v +(-2v)	
	VCOML	-15v+(-2v)	-8v +(-2v)	
	VCOMDC	-2v	-2v	

4. Voltage setting limit: VSP_0 ≥ VSPL_0 , VSP_1 ≥ VSPL_1

Restriction

R02H		Bit									
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0	Code
POF	W	0	0	0	0	0	0	0	1	0	02H
1 st Parameter	W	1	-	-	2	-	-	-	-	EDSE	00

NOTE: "-" Don't care, can be set to VDD or GND level

Description

-The command defines as:

- After power off command, driver will power off base on power off sequence.
- After power off command, BUSY N signal will drop from high to low. When finish the power off sequence, BUSY_N singal will rise from low to high.
- Power off command will turn off charge pump, T-con, source driver, gate driver, VCOM, temperature sensor, but register and SRAM data will keep until VDD off.
- SD output and VCOM will base on previous condition. It may have two conditions: 0v or floating.

1st parameter

Bit	Name	Description
		EPD Discharge Trigger
0	EDSE	0 : Disable EPD discharge (default)
		1 : Enable EPD discharge

Restriction

This command only active when BUSY_N = "1".



R03H		Bit									
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0	Code
PFS	W	0	0	0	0	0	0	0	1	1	03H
1 st Parameter	W	1	2		T_VDPG_OFF [1:0]		-		T_VDS_OFF [1:0]		00h
2 nd Parameter	W	1		VGP_LEN[3:0]			VGP_EXT[3:0]				54h
3 rd Parameter	W	1		XON_I	DLY[3:0]			XON_I	LEN[3:0]		44h

NOTE: "-" Don't care, can be set to VDD or GND level escription -The command defines as :

esc	

		ra		

Bit	Name	Description
1-0	T_VDS_OFF	Power off sequence of VSP /VSN 00: 20 ms (default) 01: 40 ms 10: 60 ms 11: 80 ms
5-4	T_VDPG_OFF	Power off sequence of VGP and VGN 00: 20 ms (default) 01: 40 ms 10: 60 ms 11: 80 ms

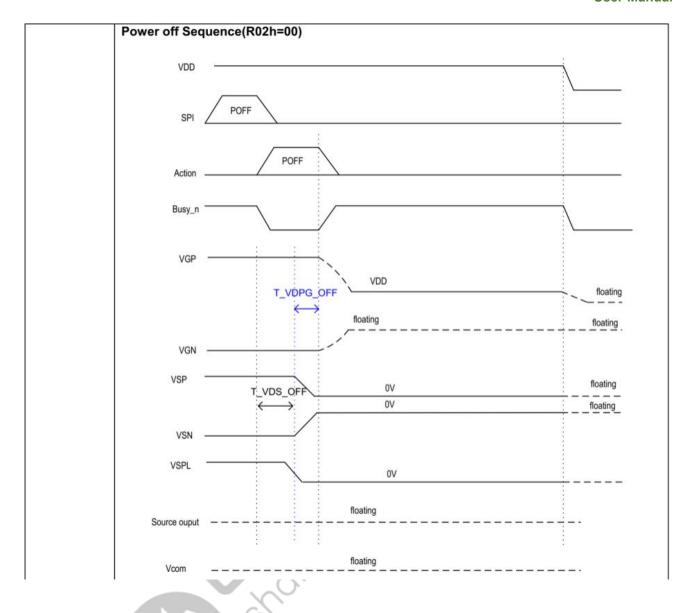
2nd Parameter

Bit	Name	Description
	0.	VGP extension time
		0000: 0 ms
		0001: 500 ms
		0010: 1000 ms
		0011: 1500 ms
		0100: 2000 ms (default)
		0101: 2500 ms
1-0	VGP_EXT	0110: 3000 ms
5.08		0111: 3500 ms
		1000: 4000 ms
		1001: 4500 ms
		1010: 5000 ms
		1011: 5500 ms
		1100: 6000 ms
		1101: 6500 ms
		When power off, the length of time VGP stay 10V
		0000: 0 ms
		0001: 500 ms
		0010: 1000 ms
		0011: 1500 ms
		0100: 2000 ms
		0101: 2500 ms (default)
7-4	VGP_LEN	0110: 3000 ms
10000	The second secon	0111: 3500 ms
		1000: 4000 ms
		1001: 4500 ms
		1010: 5000 ms
		1011: 5500 ms
		1100: 6000 ms
	E1	1101: 6500 ms

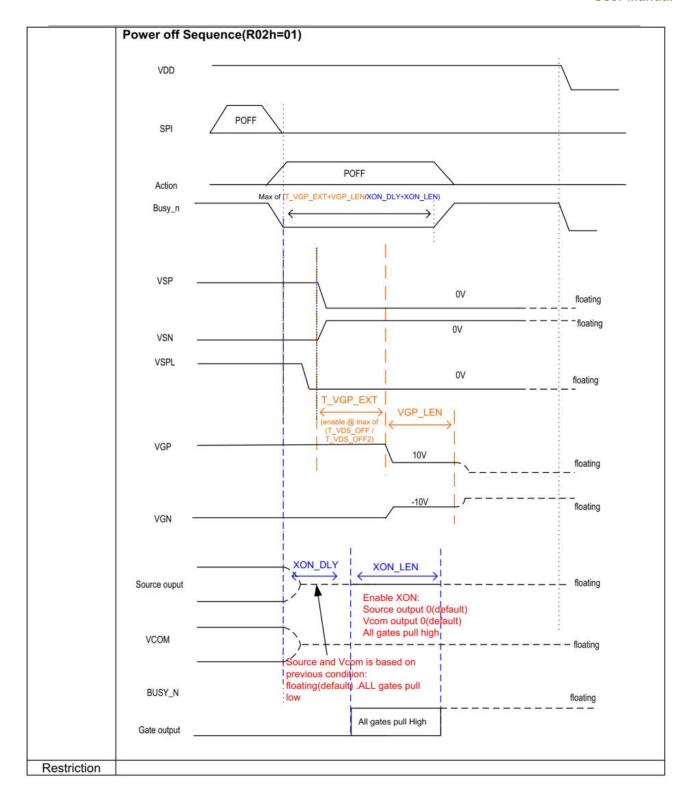


Bit	Name	Description
3-0	XON_LEN	XON enable time 0000: 0 ms 0001: 500 ms 0010: 1000 ms 0011: 1500 ms 0110: 2000 ms (default) 0101: 2500 ms 0110: 3000 ms 0111: 3500 ms 1000: 4000 ms 1001: 4500 ms 1010: 5000 ms 1010: 5000 ms 1010: 6000 ms
7-4	XON_DLY	XON delay time 0000: 0 ms 0001: 500 ms 0010: 1000 ms 0011: 1500 ms 0110: 2000 ms (default) 0101: 2500 ms 0110: 3000 ms 0111: 3500 ms 1000: 4000 ms 1001: 4500 ms 1010: 5000 ms 1010: 5000 ms











R04H		Bit									
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0	Code
PON	W	0	0	0	0	0	0	1	0	0	04H

Description	After power on command, driver will power on base on power on sequence. After power on command, BUSY_N signal will drop from high to low. When finishing the power on sequence, BUSY_N signal will rise from low to high.
Restriction	This command only active when BUSY_N = "1".

R06H		Bit									
Inst/Para	R/W	D/CX	D7	D6	D5	D5 D4 D3 D2 D1 D0					Code
BTST	W	0	0	0	0	0	0	1	1	0	06H
1 st Parameter	W	1	1	-	-	-	PHB_S	FT [1:0]	PHA_S	FT [1:0]	17h
2 nd Parameter	W	1	-	-	PHA_ON [5:0]						02h
3 rd Parameter	W	1	-	-			PHA	OFF [5:0]			07h
4 th Parameter	W	1	í				PHB	ON [5:0]			02h
5 th Parameter	W	1	·			PHB_OFF [5:0]					
6 th Parameter	W	1	ı	-	PHC_ON [5:0]						02h
7 th Parameter	W	1		-			PHC	OFF [5:0]			07h

NOTE: "-" Don't care, can be set to VDD or GND level

-The command	define as	follows:
--------------	-----------	----------

Bit	Name	Description
		Soft start period of phase A:
		00: 10mS (default)
1-0	PHA_SFT	01: 20mS
		10: 30mS
		11: 40mS
		Soft start period of phase B:
		00: 10mS (default)
3-2	PHB_SFT	01: 20mS
		10: 30mS
		11: 40mS

		Bit[5:0]	Description	Bit[5:0]	Description	Bit[5:0]	Description
		000000	strength1	010110	strength23	101100	strength45
		000001	strength2	010111	strength24	101101	strength46
		000010	strength3	011000	strength25	101110	strength47
		000011	strength4	011001	strength26	101111	strength48
Description		000100	strength5	011010	strength27	110000	strength49
Description		000101	strength6	011011	strength28	110001	strength50
		000110	strength7	011100	strength29	110010	strength51
		000111	strength8	011101	strength30	110011	strength52
		001000	strength9	011110	strength31	110100	strength53
	Driving	001001	strength10	011111	strength32	110101	strength54
	strength of	001010	strength11	100000	strength33	110110	strength55
	PHA_ON & PHB ON &	001011	strength12	100001	strength34	110111	strength56
	PHC ON	001100	strength13	100010	strength35	111000	strength57
		001101	strength14	100011	strength36	111001	strength58
		001110	strength15	100100	strength37	111010	strength59
		001111	strength16	100101	strength38	111011	strength60
		010000	strength17	100110	strength39	111100	strength61
		010001	strength18	100111	strength40	111101	strength62
		010010	strength19	101000	strength41	111110	strength63
		010011	strength20	101001	strength42	111111	strength64
		010100	strength21	101010	strength43		
		010101	strength22	101011	strength44		



Description	Bit[5:0]	Description	Bit[5:0]	Description	Bit[5:0]	Description
	000000	Period1	010110	Period23	101100	Period45
	000001	Period2	010111	Period24	101101	Period46
	000010	Period3	011000	Period25	101110	Period47
	000011	Period4	011001	Period26	101111	Period48
	000100	Period5	011010	Period27	110000	Period49
	000101	Period6	011011	Period28	110001	Period50
	000110	Period7	011100	Period29	110010	Period51
100 mars -	000111	Period8	011101	Period30	110011	Period52
Minim	001000	Period9	011110	Period31	110100	Period53
OFF to settin	001001	Period10	011111	Period32	110101	Period54
PHA_		Period11	100000	Period33	110110	Period55
&	001011	Period12	100001	Period34	110111	Period56
PHB_ &		Period13	100010	Period35	111000	Period57
PHC_		Period14	100011	Period36	111001	Period58
	001110	Period15	100100	Period37	111010	Period59
	001111	Period16	100101	Period38	111011	Period60
	010000	Period17	100110	Period39	111100	Period61
	010001	Period18	100111	Period40	111101	Period62
	010010	Period19	101000	Period41	111110	Period63
	010011	Period20	101001	Period42	111111	Period64
	010100	Period21	101010	Period43		
	010101	Period22	101011	Period44		
Restriction	- 50	40.		-5 10		ADS .

R07H		Bit									
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0	Code
DSLP	W	0	0	0	0	0	0	1	1	1	07H
1 st Parameter	W	1	1	0	1	0	0	1	0	1	A5h

Description	The command define as follows:
	After this command is transmitted, the chip would enter the deep-sleep mode to save power.
	The deep sleep mode would return to standby by hardware reset.
	The only one parameter is a check code, the command would be excited if check code = 0xA5.
	809 19
Restriction	This command only active when BUSY_N = "1".



R10H		Bit								400	
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0	Code
DTM1	W	0	0	0	0	1	0	0	0	0	10H
1 st Parameter	w	1	Pix	Pixel1		Pixel2		Pixel3		Pixel4	
2 nd Parameter	W	1		:		:		:		:	00h
	w	1	Pixe	Pixel(n-3)		Pixel(n-2)		Pixel(n-1)		Pixel(n)	
M th Parameter	w	1	Pix	Pixel1		Pixel2		Pixel3		Pixel4	

1 locori	ntion
Descri	DUOH

The command define as follows:

The register is indicates that user start to transmit data, then write to SRAM. While data transmission complete, user must send command 12H. Then chip will start to send data/VCOM for panel.

Pixel [1~n][1:0]: 2-bit/pixel

Image Data	DDX=	1(default)	DDX=0		
Pixel[1:0]	Gray level select IP output LUT select		Gray level select	IP output LUT selec	
00b	Gray0	ogray00	Gray3	ogray03	
01b	Gray1	ogray01	Gray2	ogray02	
10b	Gray2	ogray02	Gray1	ogray01	
11b	Gray3	ogray03	Gray0	ogray00	

Restriction

ba-	345

R12H	Bit										
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0	Code
DRF	W	0	0	0	0	1	0	0	1	0	12H
1 st Parameter	W	1	-	-	-	-	-	-	-	AC/DC VCOM	00h

NOTE: "-" Don't care, can be set to VDD or GND level

_			
Des	scr	int	tion

-The command defines as :

While users send this command, driver will refresh display (data/VCOM) base on SRAM data and LUT.

AC/DC VCOM:

0: AC VCOM, VCOM will follow LUTC when updating image. (default)

1: DC VCOM, VCOM will always be VCOMDC when updating image

After display refresh command, BUSY_N signal will become "0"

Restriction

This command only actives when BUSY_N = "1"

R17H		Bit									
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0	Code
Auto Sequence	W	0	0	0	0	1	0	1	1	1	17H
1 st Parameter	W	1	Code[7]	Code[6]	Code[5]	Code[4]	Code[3]	Code[2]	Code[1]	Code[0]	A5h



Restriction

Description	The command can enable the internal sequence to execute several commands continuously. The successive execution can minimize idle time to avoid unnecessary power consumption and reduce the complexity of host's control procedure. The sequence contains several operations, including PON, DRF, POF, DSLP. AUTO (0x17) + Code(0xA5) = (PON→DRF→POF) AUTO (0x17) + Code(0xA7) = (PON→DRF→POF→DSLP)
Restriction	This command only actives when BUSY_N = "1".

R30H		Bit									
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0	Code
PLL	W	0	0	0	1	1	0	0	0	0	30H
1 st Parameter	W	1	-	~	-		Dyna		FR[2:0]		02h

NOTE: "-" Don't care, can be set to VDD or GND level Description -The command defines as: The command controls the PLL clock frequency. The PLL structure must support the following frame rates: Dynamic frame rate bit3 0 Disable(default) Enable 1 Frame rate FR[2:0] 000 12.5 Hz 001 25 Hz 50 Hz(default) 010 011 65 Hz 100 75 Hz 101 85 Hz 110 100 Hz 111 120 Hz -Horizental remark hsync H active de 231 clk -Vertical vsync V active 351 lines



R40H		Bit									
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0	Code
TSC	W	0	0	1	0	0	0	0	0	0	40H
1 st Parameter	R	1	D10/TS[9]	D9/TS[8]	D8/TS[7]	D7/TS[6]	D6/TS[5]	D5/TS[4]	D4/TS[3]	D3/TS[2]	
2nd Parameter	R	1	D2/TS[1]	D1/TS[0]	D0	-	145	-	-	-	-

NOTE: "-" Don't care, can be set to VDD or GND level

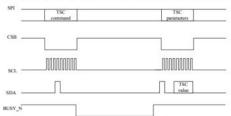
D		4.	
Desc	crin	TIC	۱r

-The command define as follows:

This command indicates the temperature value.

If R41H(TSE) bit7 set to 0, this command reads internal temperature sensor value.

If R41H(TSE) bit7 set to 1, this command reads external (LM75) temperature sensor value



TS[9:2]/D[10:3]	T (°C)	TS[9:2]/D[10:3]	T (°C)	TS[9:2]/D[10:3]	T (°C)
11100111	-25	0000000	0	00011001	25
11101000	-24	0000001	1	00011010	26
11101001	-23	0000010	2	00011011	27
11101010	-22	00000011	3	00011100	28
11101011	-21	00000100	4	00011101	29
11101100	-20	00000101	5	00011110	30
11101101	-19	00000110	6	00011111	31
11101110	-18	00000111	7	00100000	32
11101111	-17	00001000	8	00100001	33
11110000	-16	00001001	9	00100010	34
11110001	-15	00001010	10	00100011	35
11110010	-14	00001011	11	00100100	36
11110011	-13	00001100	12	00100101	37
11110100	-12	00001101	13	00100110	38
11110101	-11	00001110	14	00100111	39
11110110	-10	00001111	15	00101000	40
11110111	-9	00010000	16	00101001	41
11111000	-8	00010001	17	00101010	42
11111001	-7	00010010	18	00101011	43
11111010	-6	00010011	19	00101100	44
11111011	-5	00010100	20	00101101	45
11111100	-4	00010101	21	00101110	46
11111101	-3	00010110	22	00101111	47
11111110	-2	00010111	23	00110000	48
11111111	-1	00011000	24	00110001	49

TS[1:0]	T (°C)
00	+0
01	+0.25
10	+0.5
11	+0.75

Restriction This command only actives when BUSY_N = "1".



R41H		Bit									
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0	Code
TSE	W	0	0	1	0	0	0	0	0	1	41H
1 st Parameter	W	1	TSE	-	TO[5]	TO[4]	TO[3]	TO[2]	TO[1]	TO[0]	00h

NOTE: "-" Don't care, can be set to VDD or GND level

Description

-The command defines as: This command indicates the driver IC temperature sensor enable and calibration function.

Reserve one temperature offset TO[3:0] for calibration 1. TO[3]: mean '+' or '-' , while 0 is '+' ; 1 is '-' 2. TO[2:0]: mean temperature offset value

Bit	Name	Description
3-0	TO[3:0]	Temperature level: 0000: +0°C (default) 0001: +0.5°C 0010: +1°C 0011: +1.5°C 0100: +2°C 0101: +2.5°C 0110: +3°C 0111: +3.5°C 1000: -4°C 1001: -3.5°C 1010: -3°C 1011: -2.5°C 1100: -2°C 1101: -1.5°C 1110: -1°C 1111: -0.5°C
5-4	TO[5:4]	0: +0.0°C (default) 1: +0.25°C
7	TSE	Internal temperature sensor enable 0: Internal temperature sensor enable.(default) 1: Internal temperature sensor disable, using external temperature sensor.

This command only actives after R04H(PON) Restriction



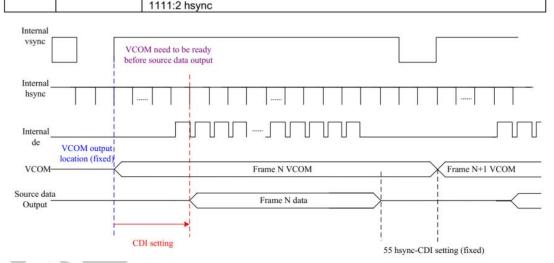
R50H		Bit									
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0	Code
CDI	W	0	0	1	0	1	0	0	0	0	50H
1 st Parameter	W	1	VBD[2]	VBD[1]	VBD [0]	DDX	CDI[3]	CDI[2]	CDI[1]	CDI[0]	97h

NOTE: "-" Don't care, can be set to VDD or GND level

Description	-The command defines as:
	1 _{st} Parameter:

CDI[1:0]: This command indicates the interval of VCOM and data output. When setting the vertical back porch, the total blanking will be keep (55hsync).

Bit	Name	Description
3-0	Name CDI[3:0]	Vcom and data interval 0000: 17 hsync 0001:16 hsync 0010:15 hsync 0011:14 hsync 0100:13 hsync 0101:12 hsync 0110:11 hsync 0110:11 hsync 0110:110 hsync(default)
	05,(6:0)	1000:9 hsync 1001:8 hsync 1010:7 hsync 1011:6 hsync 1100:5 hsync 1101:4 hsync 1110:3 hsync 1111:2 hsync





VBD[2:0]: Border data selection. (from LUT output by IP port border_w[1:0])

This register will make boarder pin output being mapped to a certain gray scale.

Bit 4	Bit7-5	Description	IP setting for Border LUT		
DDX	VBD[2:0]	Gray level	select		
	000	Floating	N/A		
	001	Gray3	border_buf=011		
0	010	Gray2	border_buf=010		
	011	Gray1	border_buf=001		
	100	Gray0	border_buf=000		
The state of the s	000	Gray0	border_buf=000		
	001	Gray1	border_buf=001		
1 (default)	010	Gray2	border_buf=010		
	011	Gray3	border_buf=011		
	100	Floating	N/A		

Border output voltage level: The level selection is based on mapping LUT data.

Ex: Gray 1 waveform is mapping to 15V, without VCOM offset, the real output on Boarder pin shall be 15V.

Boarder output will follow FOPT definition being defined in R00h.

Restriction

R51H Bit Inst/Para R/W D4 D2 D/CX D7 D₆ D₅ D3 D₁ D₀ Code LPD 0 1 1 0 0 0 51H 1st Parameter R LPD

NOTE: "-" Don't care, can be set to VDD or GND level

Description

-The command defines as:

This command indicates the input power condition. Host can read this data to understand the battery's condition.

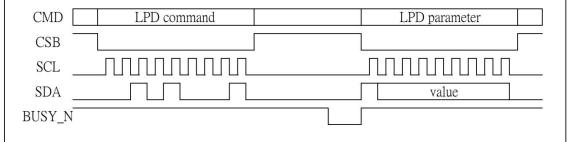
01

When LPD="1", system input power is normal.

When LPD="0", system input power is lower (VDD<2.5v, which could be select in RE4H (LVSEL)).

1st Parameter:

Bit	Name	Description
0	LPD	0: Low power input 1: Normal status



Restriction - This command only actives when BUSY_N = "1".



R61H		Bit									
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0	Code
TRES	W	0	0	1	1	0	0	0	0	1	61H
1 st Parameter	W	1	-	-	-	-	-	-	HRES(9)	HRES(8)	00h
2 nd Parameter	W	1	HRES(7)	HRES(6)	HRES(5)	HRES(4)	HRES(3)	HRES(2)	0	0	00h
3 rd Parameter	W	1	-	•	-	-	-	-	VRES(9)	VRES(8)	00h
4 th Parameter	W	1	VRES(7)	VRES(6)	VRES(5)	VRES(4)	VRES(3)	VRES(2)	VRES(1)	VRES(0)	00h

NOTE: - Don	care, can be set to VDD or GND level
Description	-The command define as follows:
	When using register:
	Horizontal display resolution = HRES
	Vertical display resolution = VRES
	Channel disable calculation:
	GD : First G active = G0; LAST active GD= first active +VRES[9:0] -1
	SD : First active channel: =S0 ; LAST active SD= first active +HRES[9:2]*8-1
	EX :200X384
	GD: First G active = G0
	LAST active GD= 0+384-1= 383; (G383)
	SD : First active channel: =S0
	LAST active SD=0+50*4-1=199; (S199)
	R61H = 00h,C8h, 01h, 80h (解析度直接轉 16 進制即為設定值)
	Note: Only supports source 200.ch for source 184ch. above
Restriction	

R65H		Bit									
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0	Code
GSST	W	0	0	1	1	0	0	1	0	1	65H
1 st Parameter	W	1	-	-	-	-	-	-	S_start[9]	S_start[8]	00h
2 nd Parameter	W	1	S_start[7]	S_start[6]	S_start[5]	S_start[4]	S_start[3]	S_start[2]		-	00h
3 rd Parameter	W	1	-	2	-	-	-	~	G_start[9]	G_start[8]	00h
4 th Parameter	W	1	G_start[7]	G_start[6]	G_start[6]	G_start[4]	G_start[3]	G_start[2]	G_start[1]	G_start[0]	00h

NOTE: "-" Don't care, can be set to VDD or GND level

Description	-The command define as follows: 1.S_Start [9:2] describe which source output line is the first date line 2.G_Start[9:0] describe which gate line is the first scan line
Restriction	



Restriction

R70H	,	Bit									
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0	Code
REV	W	0	0	1	1	1	0	0	0	0	70H
1 st Parameter	R	1	0	0	0	0	0	0	1	1	03h
2 nd Parameter	R	1	0	0	0	0	0	0	1	0	02h
3 rd Parameter	R	1	0	0	0	0	0	0	0	1	01h

NOTE: "-" Don't care, can be set to VDD or GND level

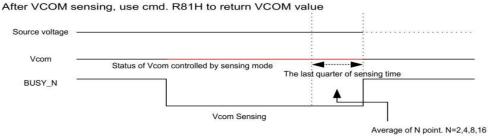
Description	-The comman	nd defines as:						
-	The LUT RE	The LUT_REV is read from:						
	1st & 2nd & 3nd	d Parameter :						
	Bit	Description						
	3-0	CHIP_REV						

R80H	ĺ	Bit									
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0	Code
AMV	W	0	1	0	0	0	0	0	0	0	80H
1 st Parameter	W	1	1585	(=)	AMVT[1]	AMVT[0]	XON	AMVS	AMV	AMVE	10h

NOTE: "-" Don't care, can be set to VDD or GND level

Description -The command defines as:
This command indicates the IC status. Host can read this data to understand the IC status.

Bit	Name	Description
		AMVE: Auto Measure Vcom Setting
0	AMVE	0: Auto measure VCOM disable (default)
		1: Auto measure VCOM enable
		AMV: Analog signal
1	AMV	0:Get Vcom value from R81h(default)
		1:Get Vcom value in analog signal
		AMVS: setting for Source output of AMV
2	AMVS	0: Source output 0V during Auto Measure VCOM period.
2	AWVS	(default)
		1: Source output VSPL_0 during Auto Measure VCOM p
		XON: setting for all Gate ON of AMV
3	XON	Gate normally scan during Auto Measure VCOM period
0	XOI	(default)
		1: All Gate ON during Auto Measure VCOM period.
		The sensing time of VCOM detection
		00: 5s (default)
5-4	AMVT[1:0]	01: 10s
		10: 15s
		11: 20s



Note:

1.VCOM設定至最小0V(R82h=80h)

2.外部穩壓電容floating

Restriction This command only actives when BUSY_N = "1"



R81H		Bit									
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0	Code
VV	W	0	1	0	0	0	0	0	0	1	81H
1 st Parameter	R	1	-	-	VV[5]	VV[4]	VV[3]	VV[2]	VV[1]	VV[0]	-

Description	-The command defines as:
•	This command could get the VCOM value

1st Parameter:

		VCOM va	ilue		Description							
		VCOM[6:0]	Voltage(V)	VCOM[6:01	Voltage(V)	VCOM[6	6:0]	Voltage(V)		
		0000000	_	0	0011100		-1.4	0111000		-2.8		
		0000001	01h	-0.05	0011101	1Dh	-1.45	0111001	39h	-2.85		
		0000010	02h	-0.1	0011110	1Eh	-1.5	0111010	3Ah	-2.9		
		0000011	03h	-0.15	0011111	1Fh	-1.55	0111011	3Bh	-2.95		
		0000100	04h	-0.2	0100000	20h	-1.6	0111100	3Ch	-3		
		0000101	05h	-0.25	0100001	21h	-1.65	0111101	3Dh	-3.05		
		0000110	06h	-0.3	0100010	22h	-1.7	0111110	3Eh	-3.1		
		0000111	07h	-0.35	0100011	23h	-1.75	0111111	3Fh	-3.15		
		0001000	08h	-0.4	0100100	24h	-1.8	1000000	40h	-3.2		
		0001001	09h	-0.45	0100101	25h	-1.85	1000001	41h	-3.25		
		0001010	0Ah	-0.5	0100110	26h	-1.9	1000010	42h	-3.3		
		0001011	0Bh	-0.55	0100111	27h	-1.95	1000011	43h	-3.35		
		0001100	0Ch	-0.6	0101000	28h	-2	1000100	44h	-3.4		
6-0	VV[6:0]	0001101	0Dh	-0.65	0101001	29h	-2.05	1000101	45h	-3.45		
		0001110	0Eh	-0.7	0101010	2Ah	-2.1	1000110	46h	-3.5		
		0001111	0Fh	-0.75	0101011	2Bh	-2.15	1000111	47h	-3.55		
		0010000	10h	-0.8	0101100	2Ch	-2.2	1001000	48h	-3.6		
		0010001	11h	-0.85	0101101	2Dh	-2.25	1001001	49h	-3.65		
		0010010	12h	-0.9	0101110	2Eh	-2.3	1001010	4Ah	-3.7		
		0010011	13h	-0.95	0101111	2Fh	-2.35	1001011	4Bh	-3.75		
		0010100	14h	-1	0110000	30h	-2.4	1001100	4Ch	-3.8		
		0010101	15h	-1.05	0110001	31h	-2.45	1001101	4Dh	-3.85		
		0010110	16h	-1.1	0110010	32h	-2.5	1001110	4Eh	-3.9		
		0010111	17h	-1.15	0110011	33h	-2.55	1001111	4Fh	-3.95		
		0011000	18h	-1.2	0110100	34h	-2.6	1010000	50h	-4		
		0011001	19h	-1.25	0110101	35h	-2.65	other		-4		
		0011010	1Ah	-1.3	0110110	36h	-2.7					
		0011011	1Bh	-1.35	0110111	37h	-2.75	6				



R82H		Bit									
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0	Code
VDCS	W	0	1	0	0	0	0	0	1	0	82H
1 st Parameter	W	1	MTP_VCM	VDCS[6]	VDCS[5]	VDCS [4]	VDCS [3]	VDCS [2]	VDCS [1]	VDCS [0]	00h

Description	 The command defines a 	as:
	Ti-!	

This command set the VCOM DC value. Driver will base on this value for VCM_DC.

1st Parameter:

Bit	Name	VCOM well			Des	cription			
		VCOM val		e(V) VCOM	16:01	Voltage(V)	VCOM[6:01	Voltage(V
		0000000	-			-1.4	0111000	-	-2.8
		0000001				-1.45	0111001		-2.85
		0000010			1000000	-1.5	0111010		-2.9
		0000011	100			-1.55	0111011	3Bh	-2.95
		0000100	04h -0.2	0100000	20h	-1.6	0111100	3Ch	-3
		0000101	05h -0.2	0100001	21h	-1.65	0111101	3Dh	-3.05
		0000110	06h -0.3	0100010	22h	-1.7	0111110	3Eh	-3.1
		0000111	07h -0.3	0100011	23h	-1.75	0111111	3Fh	-3.15
		0001000	08h -0.4	0100100	24h	-1.8	1000000	40h	-3.2
		0001001	09h -0.4	0100101	25h	-1.85	1000001	41h	-3.25
		0001010	OAh -0.5	0100110	26h	-1.9	1000010	42h	-3.3
		0001011	OBh -0.5	0100111	27h	-1.95	1000011	43h	-3.35
		0001100	OCh -0.6	0101000	28h	-2	1000100	44h	-3.4
6-0	VDCS[6:0]	0001101	ODh -0.6	0101001	29h	-2.05	1000101	45h	-3.45
		0001110	OEh -0.7	0101010	2Ah	-2.1	1000110	46h	-3.5
		0001111	0Fh -0.7	0101011	2Bh	-2.15	1000111	47h	-3.55
		0010000	10h -0.8	0101100	2Ch	-2.2	1001000	48h	-3.6
		0010001	11h -0.8	0101101	2Dh	-2.25	1001001	49h	-3.65
		0010010	12h -0.9	0101110	2Eh	-2.3	1001010	4Ah	-3.7
		0010011	13h -0.9	0101111	2Fh	-2.35	1001011	4Bh	-3.75
		0010100	14h -1	0110000	30h	-2.4	1001100	4Ch	-3.8
		0010101	15h -1.0	0110001	31h	-2.45	1001101	4Dh	-3.85
		0010110	16h -1.1	0110010	32h	-2.5	1001110	4Eh	-3.9
		0010111	17h -1.1	5 0110011	33h	-2.55	1001111	4Fh	-3.95
		0011000	18h -1.2	0110100	34h	-2.6	1010000	50h	-4
		0011001	19h -1.2	0110101	35h	-2.65	other		-4
		0011010	1Ah -1.3	0110110	36h	-2.7			
		0011011	1Bh -1.3	5 0110111	37h	-2.75	1		



R83H						Bit					
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0	Code
PTL	W	0	1	0	0	0	0	0	1	1	83H
1 st Parameter	W	1	-	-	-	-	-	-	HRST[9]	HRST[8]	00h
2 nd Parameter	W	1	HRST[7]	HRST[6]	HRST[5]	HRST[4]	HRST[3]	HRST[2]	-	-	00h
3 rd Parameter	W	1	-	-	-	-	-	-	HRED[9]	HRED[8]	00h
4 th Parameter	W	1	HRED[7]	HRED[6]	HRED[5]	HRED[4]	HRED[3]	HRED[2]	-	-	00h
5 th Parameter	W	1	-	1.5	-	i.=	-	-	VRST[9]	VRST[8]	00h
6 th Parameter	W	1	VRST[7]	VRST[6]	VRST[5]	VRST[4]	VRST[3]	VRST[2]	VRST[1]	VRST[0]	00h
7 th Parameter	W	1	-	-	-	-	-	-	VRED[9]	VRED[8]	00h
8 th Parameter	W	1	VRED[7]	VRED[6]	VRED[5]	VRED[4]	VRED[3]	VRED[2]	VRED[1]	VRED[0]	00h
9 th Parameter	W	1	-	2	-	-	-		-	PMODE	00h

NOTE: "-" Don't care, can be set to VDD or GND level

Description -This command sets partial window. Name Description HRST[9:2] Horizontal start address Horizontal end address. HRED must be greater than HRST. HRED[9:2] VRST[9:0] Vertical start address. Vertical end address. VRED must be greater than VRST. VRED[9:0] 0: disable partial mode(default) **PMODE** 1: enable partial mode Note: No matter HRST[1:0], HRST[9:8], HRED[9:8], VRST[9], VRED[9] value being filled, it's always be No matter HRED[1:0] value being filled, it's always be 11b. Gates scan both inside and outside of the partial window. Partial display flow: Initial Code Partial Window Register setting (PMODE=1) (R83H) DTM1 (R10H) Power on (R04H) Display (R12H=00) Restriction



	R90H		Bit									
	Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0	Code
Ī	PGM	W	0	1	0	1	0	0	0	0	0	A0H

Description	-The command define as follows: After this command is issued, the chip would enter the program mode. The mode would return to standby by hardware reset.
Restriction	This command only actives when BUSY_N = "1".

R91H						Bit					
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0	Code
APG	W	0	1	0	0	1	0	0	0	1	91H

NOTE: "-" Don't care, can be set to VDD or GND level

Description	-The command define as follows:
	After this command is transmitted, the programming state machine would be activated.
Restriction	The BUSY flag would change state from 0 to 1 while the programming is completed.

TOSTICTOR	THE DE	JO I III	g would c	nange su	ate moni o	to i willic	tile prog	ranning	is comple	icu.	
R92H						Bit					
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0	Code
RMTP	W	0	1	0	0	1	0	0	1	0	92H
1 st Parameter	R	1				Dun	nmy				-
2 nd Parameter	R	1			The da	ta of addres	s 0x000 in th	ne MTP			-
3 rd Parameter	R	1			The da	ta of addres	s 0x001 in th	ne MTP			-
4 th Parameter	R	1				3					3
5 th Parameter	R	1		The data of address (n-1) in the MTP						-	
6 th ~(m-1) th Parameter	R	1									-
m th Parameter	R	1			The o	data of addre	ess (n) in the	MTP			-

NOTE: "-" Don't care, can be set to VDD or GND level

NOTE. DOI	rt care, can be set to VBB or GNB lever
Description	-The command define as follows:
	The command is used for reading the content of MTP for checking the data of programming.
	The value of (n) is depending on the amount of programmed data, the max address = 0x17FF.
Restriction	This command only actives when BUSY_N = "1".

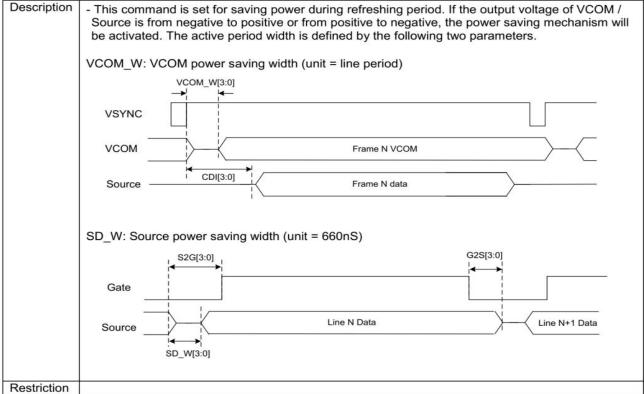


R9FH						Bit					
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0	Code
RMRB	W	0	1	0	0	1	1	1	1	1	9FH
1 st Parameter	R	1	6			Dun	nmy				
2 nd Parameter	R	1			The dat	a of address	0x16F7 in	the MTP			00h
3 rd Parameter	R	1	50	:				00h			
:	R	1		:				00h			
97 th Parameter	R	1		<u>:</u>				00h			
98 th Parameter	R	1	0	:				00h			
101 th Parameter	R	1		The data of address 0x175A in the MTP				00h			

Description	-The command define as follows: The command is used for reading the content of MTP Reserved Byte for checking the data of programming. This command could read these information from MTP directly.
Restriction	This command only actives when BUSY_N = "1".

RE3H	1	Bit									
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0	Code
PWS	W	0	1	1	1	0	0	0	1	1	E3H
1 st Parameter	W	1		VCOM_W[3:0]			SD_W[3:0]				00h

NOTE: "-" Don't care, can be set to VDD or GND level





RE4H		Bit									
Inst/Para	R/W	D/CX	D7	D6	D5	D4	D3	D2	D1	D0	Code
LVSEL	W	0	1	1	1	0	0	1	0	0	E4H
1 st Parameter	W	1	2	-	-	-	12.5	-	LVD_S	SEL[1:0]	03h

NOTE: "-" Don't care, can be set to VDD or GND level

Description	LVD_SEL[1:0]: Low Power Vo	oltage Selection	
	LVD_SEL[1:0]	LVD value	
	00	< 2.2 V	
	01	< 2.3 V	
	10	< 2.4 V	
	11	< 2.5 V (default)	
Restriction			
Restriction		-	
	Sh	Ne Some	



specification.

8. HANDLING, SAFETY, AND ENVIRONMENT REQUIREMENTS

WARNING

The display glass may break when it is dropped or bumped on a hard surface. Handle with care. Should the display break, do not touch the electrophoretic material. In case of contact with electrophoretic material, wash with water and soap.

CAUTION

The display module should not be exposed to harmful gases, such as acid and alkali gases, which corrode electronic components.

Disassembling the display module can cause permanent damage and invalidates the warranty agreements.

Observe general precautions that are common to handling delicate electronic components. The glass can break and front surfaces can easily be damaged. Moreover the display is sensitive to static electricity and other rough environmental conditions.

Data sheet status							
Product specification	This data sheet contains final product specifications.						
	Limiting values						
Limiting values given are in accordance with the Absolute Maximum Rating System (IEC							
134).							
Stress above one or more of	the limiting values may cause permanent damage to the						
device. These are stress rating	s only and operation of the device at these or at any other						
conditions above those given	in the Characteristics sections of the specification is not						
implied. Exposure to limiting values for extended periods may affect device reliability.							
	Application information						
Where application information is given, it is advisory and does not form part of the							



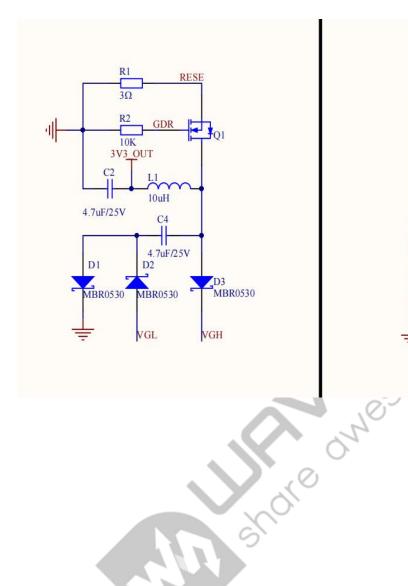
9. RELIABILITY TEST

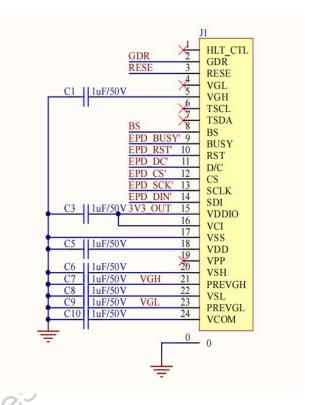
NO	Test items	Test condition
1	Low-Temperature Storage	T = -25°C, 240 h Test in white pattern
2	High-Temperature Storage	T=60°C, RH=35%, 240h Test in white pattern
3	High-Temperature Operation	T=40°C, RH=35%, 240h
4	Low-Temperature Operation	0°C, 240h
5	High Temperature High-Humidity Operation	T=40°C , RH=80%, 240h
6	High Temperature High Humidity Storage	T=50°C , RH=90%, 240h Test in white pattern
7	Temperature Cycle	1 cycle: [-25°C 30min]→ [+60 °C 30 min] : 50 cycles Test in white pattern
8	UV exposure Resistance	765W/m² for 168hrs, 40°C Test in white pattern
9	ESD Gun	Air+/-15KV; Contact +/-8KV (Test finished product shell, not display only) Air+/-8KV; Contact +/-6KV (Naked EPD display, not including IC and FPC area) Air+/-4KV; Contact +/-2KV (Naked EPD display, including IC and FPC area)

Note: Put in normal temperature for 1 hour after test finished, display performance is OK.



10. TYPICAL APPLICATION CIRCUIT

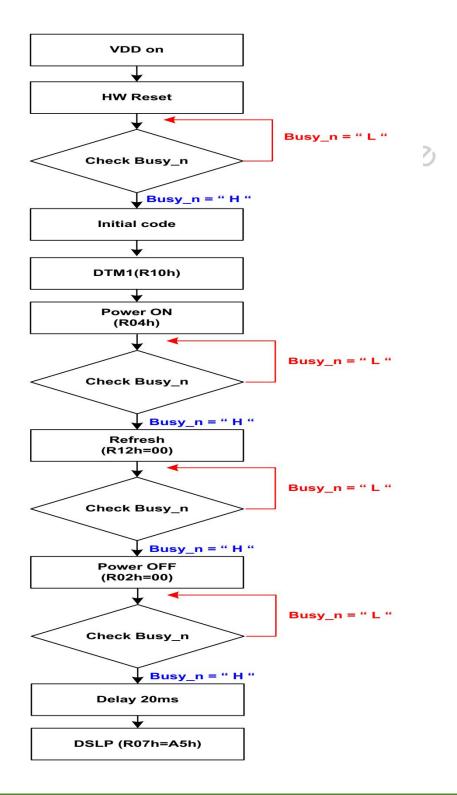






11. TYPICAL OPERATING SEQUENCE

11.1 NORMAL OPERATION FLOW

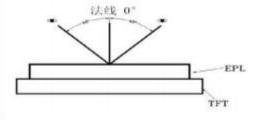




12. INSPECTION METHOD AND CONDITION

12.1 INSPECTION CONDITION

Item	Condition
Illuminance	800~1500 lux
Temperature	22℃±3℃
Humidity	55±10 %RH
Distance	≥30cm
Angle	Vertical fore and aft 45
Inspection method	By eyes



12.2 ZONE DEFINITION

A Zone: Active area B Zone: Border zone

C Zone: From B zone edge to panel edge

12.3 GENERAL INSPECTION STANDARDS FOR PRODUCTS

12.3.1 APPEARANCE INSPECTION STANDARD

Inspect	ion item	Fi	gure	A zone inspection standard	B/C zone	Inspection method	MAJ/ MIN
	Spot defects such as dot, foreign matter, air bubble, and dent etc.	Diameter D=(L+W)/2 (L-length, W-width) Measuring method shown in the figure below D=(L+W)/2	The distance between the two spots should not be less than 10mm	$\begin{array}{llllllllllllllllllllllllllllllllllll$	Foreign matter D≤1mm Pass	Check by eyes Film gauge	MIN



Insp	ection item	F	igure	A zone inspection standard	B/C zone	Inspection method	MA J/ MI N
Line defects	Line defects such as scratch, hair etc.	L-Length, W-Width, (W/L)<1/4 Judged by line, (W/L)≥1/4 Judged by dot	The distance between the two lines should not be less than 5mm	7.5"-13.3"Module (Not include 7.5"): L>10mm,N=0 W>0.8mm, N=0 5mm≤L≤10mm, 0.5mm≤W≤0.8mm N≤2 L≤5mm, W≤0.5mm Ignore 4.2"-7.5"Module (Not include 4.2"): L>8mm,N=0 W>0.2mm, N=0 2mm≤L≤8mm, 0.1mm≤W≤0.2mm N≤4 L≤2mm, W≤0.1mm Ignore Module below 4.2": L>5mm,N=0 W>0.2mm, N=0 2mm≤L≤5mm, 0.1mm≤W≤0.2mm N≤4 L≤2mm, W≤0.1mm Ignore	Ignore	Check by eyes Film gauge	MIN

Inspect	tion item	Figure	Inspection standard	Inspection method	MA J/ MIN
Panel chipping and crack defects	TFT panel chipping	X the length, Y the width, Z the chipping height, T the thickness of the panel	Chipping at the edge: Module over 7.5" (Include 7.5"): X≤ 6mm,Y≤1mm Z≤T N=3 Allowed Module below 7.5"(Not include 7.5"): X≤ 3mm,Y≤1mm Z≤T N=3 Allowed Chipping on the corner: IC sideX≤2mm Y≤2mm, Non-IC sideX≤1mm Y≤1mm. Allowed Note: Chipping should not damage the edge wiring. If it does not affect the display, allowed	Check by eyes. Film gauge	MIN
	Crack	玻璃裂纹	Crack at any zone of glass, Not allowed	Check by eyes. Film gauge	MIN
	Burr edge	+	No exceed the positive and negative deviation of the outline dimensions $X+Y \leq 0.2mm$ Allowed	Calliper	MIN
	Curl of panel	H Curl height	Curl height H≤Total panel length 1% Allowed	Check by eyes	MIN



Inspec	tion item	Figure	Inspection standard	Inspecti on method	MAJ / MIN
PS defect	Water proof film		1. Waterproof film damage, wrinkled, open edge, not allowed 2. Exceeding the edge of module(according to the lamination drawing) Not allowed 3. Edge warped exceeds height of technical file, not allowed	Check by eyes	MIN
RTV defect	Adhesive effect		Adhesive height exceeds the display surface, not allowed 1 .Overflow, exceeds the panel side edge, affecting the size, not allowed 2 .No adhesive at panel edge≤1mm, mo exposure of wiring, allowed 3. No adhesive at edge and corner1*1mm, no exposure of wiring, allowed Protection adhesive, coverage width within W≤1.5mm, no break of adhesive, allowed	Check by eyes	MIN
	Adhesive re-fill		Dispensing is uniform, without obvious concave and breaking, bubbling and swell, not higher than the upper surface of the PS, and the diameter of the adhesive re-filling is not more than 8mm, allowed	Check by eyes	MIN
EC defect	Adhesive bubble	防水胶涂布区 封边胶边缘 PS边缘 防水胶涂布区 Border外缘(PPL边缘)	 Effective edge sealing area of hot melt products ≥1/2 edge sealing area; Bubble a+b≥1/2 effective width, N≤3, spacing≥5mm, allowed No exposure of wiring, allowed 	Check by eyes	MIN

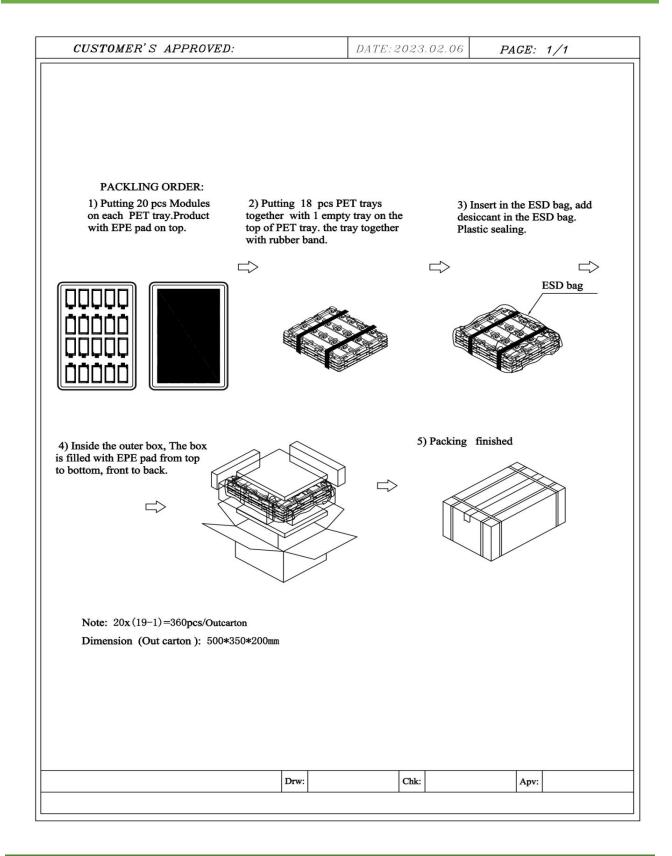
Inspecti	ion item	Figure	Inspection standard	Inspection method	MAJ/ MIN
EC defect	Adhesive effect		1. Overflow, exceeds the panel side edge, affecting the size, not allowed 2.No adhesive at panel edge≤1mm, mo exposure of wiring, allowed 3.No adhesive at edge and corner 1*1mm, no exposure of wiring, allowed 4. Adhesive height exceeds the display surface, not allowed	Visual, caliper	MIN
Silver dot adhesive defect	Silver dot adhesive		1. Single silver dot dispensing amount ≥1mm, allowed 2. One of the double silver dot dispensing amount is ≥1mm and the other has adhesive (no reference to 1mm) Allowed	Visual	MIN
defect			Silver dot dispensing residue on the panel ≤0.2mm, allowed	Film gauge	MIN
	FPC wiring		FPC, TCP damage / gold finger peroxidation, adhesive residue, not allowed	Visual	MIJ
FPC defect	FPC golden finger		The height of burr edge of TCP punching surface ≥ 0.4mm, not allowed	Caliper	MIN
	FPC damage/cr ease		Damage and breaking, not allowed Crease does not affect the electrical performance display, allowed	Check by eyes	MIN



	on item	Figure	Inspection standard	Inspection method	MAJ/ MIN
Protective	Protective	Scratch and crease on the surface but no affe	ct to protection function, allowed	Check by eyes	MIN
film defect	film	Adhesive at edge L≤5mm, W≤0.5mm, N=	2, no entering into viewing area	Check by eyes	MIN
Stain defect	Stain	If stain can be normally wiped clean by > 99	% alcohol, allowed	Visual	MIN
Pull tab defect	Pull tab	The position and direction meet the documer film can be pulled off.	nt requirements, and ensure that the protective	Check by eyes/ Manual pulling	MIN
Shading tape defect	Shading tape	Tilt≤10°, flat without warping, completely co	overing the IC.	Check by eyes/ Film gauge	MIN
Stiffener	Stiffener	Flat without warping, Exceeding the left and Left and right can be less than 0.5mm from F		Check by eyes	MIN
Label	Label/ Spraying code	The content meets the requirements of the w requirements of the technical documents.	ork sheet. The attaching position meets the	Check by eyes	MIN
			owesome		



13. PACKAGING





14. PRECAUTIONS

- (1) Do not apply pressure to the EPD panel in order to prevent damaging it.
- (2) Do not connect or disconnect the interface connector while the EPD panel is in operation.
- (3) Do not touch IC bonding area. It may scratch TFT lead or damage IC function.
- (4) Please be mindful of moisture to avoid its penetration into the EPD panel, which may cause damage during operation.
- (5) If the EPD Panel / Module is not refreshed every 24 hours, a phenomena known as "Ghosting" or "Image Sticking" may occur. It is recommended to refreshed the ESL/EPD Tag every 24 hours in use case. It is recommended that customer ships or stores the ESL/EPD Tag with a completely white image to avoid this issue.
- (6) High temperature, high humidity, sunlight or fluorescent light may degrade the EPD panel's performance. Please do not expose the unprotected EPD panel to high temperature, high humidity, sunlight, or fluorescent for long periods of time.